Special Function Logic Gate

NLSF457

Description

The NLSF457 is a single special function gate in tiny footprint package.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.7 ns t_{PD} at 5 V (typ)
- Inputs/Outputs Over-Voltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in 1.45 mm x 1.0 mm UDFN8 Package
- Chip Complexity < 100 FETs
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

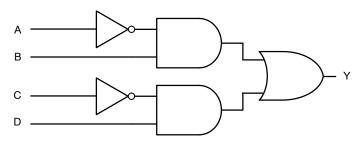


Figure 1. Logic Diagram



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UDFN8, 1.45x1, 0.35P CASE 517EB

MARKING DIAGRAM



XX = Specific Device Code

- M = Assembly Operation Code*
 - = Pb-Free Package

(Note: Microdot may be in either location) *Assembly Operation Code orientation and/or may vary depending upon manufacturing location.

PIN ASSIGNMENT

| nc | 1] | 8 | V _{CC} |
|-----|----|---|-----------------|
| D | 2 | 7 | Y |
| С | 3 | 6 | А |
| GND | 4 | 5 | В |
| | | | |

| Pin | Name | Description |
|-----|-----------------|--------------|
| 1 | nc | No Connect |
| 2 | D | Input |
| 3 | С | Input |
| 4 | GND | Ground |
| 5 | В | Input |
| 6 | А | Input |
| 7 | Y | Output |
| 8 | V _{CC} | Power Supply |

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

NLSF457

Table 1. FUNCTION TABLE

| | Input | | | | | |
|---|-------|---|---|---|--|--|
| А | В | С | D | Y | | |
| 0 | 0 | 0 | 0 | 0 | | |
| 0 | 0 | 0 | 1 | 1 | | |
| 0 | 0 | 1 | 0 | 0 | | |
| 0 | 0 | 1 | 1 | 0 | | |
| 0 | 1 | 0 | 0 | 1 | | |
| 0 | 1 | 0 | 1 | 1 | | |
| 0 | 1 | 1 | 0 | 1 | | |
| 0 | 1 | 1 | 1 | 1 | | |
| 1 | 0 | 0 | 0 | 0 | | |
| 1 | 0 | 0 | 1 | 1 | | |
| 1 | 0 | 1 | 0 | 0 | | |
| 1 | 0 | 1 | 1 | 0 | | |
| 1 | 1 | 0 | 0 | 0 | | |
| 1 | 1 | 0 | 1 | 1 | | |
| 1 | 1 | 1 | 0 | 0 | | |
| 1 | 1 | 1 | 1 | 0 | | |

MAXIMUM RATINGS

| Symbol | Parameter | | Ratings | Unit | |
|------------------------------|---|--|------------------------------|------|--|
| V _{CC} | DC Supply Voltage | | -0.5 to +6.5 | V | |
| V _{IN} | DC Input Voltage | | -0.5 to +6.5 | V | |
| V _{OUT} | DC Output Voltage Active-Mode (High or Low State) | | –0.5 to V _{CC} +0.5 | V | |
| | | Tri-State Mode (Note 1) | -0.5 to +6.5 | | |
| | | Power–Down Mode (V _{CC} = 0 V) | -0.5 to +6.5 | | |
| I _{IK} | DC Input Diode Current | V _{IN} < GND | -50 | mA | |
| I _{OK} | DC Output Diode Current | DC Output Diode Current V _{OUT} < GND | | mA | |
| I _{OUT} | DC Output Source/Sink Current | | ±50 | mA | |
| $I_{CC} \text{or} I_{GND}$ | DC Supply Current Per Supply Pin or Ground Pin | | ±100 | mA | |
| T _{STG} | Storage Temperature Range | | -65 to +150 | °C | |
| TL | Lead Temperature, 1 mm from Case for 10 |) Seconds | 260 | °C | |
| TJ | Junction Temperature Under Bias | | +150 | °C | |
| θ_{JA} | Thermal Resistance (Note 2) | UDFN8 | 231 | °C/W | |
| PD | Power Dissipation in Still Air at 125°C | UDFN8 | 541 | mW | |
| MSL | Moisture Sensitivity | • | Level 1 | | |
| F _R | Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in | | |
| V _{ESD} | ESD Withstand Voltage (Note 3) | Charged Device Model | > 2000 | V | |
| | | Human Body Model | > 1000 | | |
| ILATCHUP | Latchup Performance (Note 4) | | ±100 | mA | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.

 Applicable to devices with outputs that may be in-stated.
Measured with minimum pad spacing on an FR4 board, using 10mm – by – 1inch, 2 ounce copper trace no air flow per JESD51–7.
HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22–C101–F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.

4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | | Min | Max | Unit |
|---------------------------------|------------------------------------|------------------------------------|------|-----------------|------|
| V _{CC} | Positive DC Supply Voltage | | 1.65 | 5.5 | V |
| V _{IN} | Digital Input Voltage | | 0 | 5.5 | V |
| V _{OUT} | Output Voltage | Active Mode (High or Low State) | 0 | V _{CC} | V |
| | | Tri-State Mode (Note 1) | 0 | 5.5 | |
| | | Power Down Mode ($V_{CC} = 0 V$) | 0 | 5.5 | |
| T _A | Operating Free-Air Temperature | · · | -55 | +125 | °C |
| t _r , t _f | Input Transition Rise or Fall Rate | V _{CC} = 1.65 V to 1.95 V | 0 | 20 | nS/V |
| | | V_{CC} = 2.3 V to 2.7 V | 0 | 20 | |
| | | V_{CC} = 3.0 V to 3.6 V | 0 | 10 | 1 |
| | | V_{CC} = 4.5 V to 5.5 V | 0 | 5 | |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

| | | | | | T _A = 25°C | | T _A = −55°C | C to +125°C | |
|------------------|------------------------------|--|--|---|---|--|---|--|------|
| Symbol | Parameter | Conditions | V _{CC} (V) | Min | Тур | Max | Min | Max | Unit |
| V_{IH} | High-Level | | 1.65 to 1.95 | $0.65 \times V_{CC}$ | - | - | $0.65 \times V_{CC}$ | - | V |
| | Input Voltage | | 2.3 to 5.5 | $0.70 \times V_{CC}$ | _ | - | $0.70 \times V_{CC}$ | - | |
| V _{IL} | Low-Level | | 1.65 to 1.95 | - | - | $0.35 \times V_{CC}$ | - | $0.35 \times V_{CC}$ | V |
| | Input Voltage | | 2.3 to 5.5 | - | - | $0.30 \times V_{CC}$ | - | $0.30 \times V_{CC}$ | |
| V _{OH} | High-Level Output Voltage | | 1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5 | $\begin{matrix} V_{CC} - 0.1 \\ 1.29 \\ 1.9 \\ 2.2 \\ 2.4 \\ 2.3 \\ 3.8 \end{matrix}$ | V _{CC} 1.4 2.1 2.4 2.7 2.5 4.0 | - | $\begin{matrix} V_{CC} - 0.1 \\ 1.29 \\ 1.9 \\ 2.2 \\ 2.4 \\ 2.3 \\ 3.8 \end{matrix}$ | - | V |
| V _{OL} | Low-Level Output Voltage | | 1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5 | - | 0.08 0.2 0.22 0.28 0.38 0.42 | 0.1 0.24 0.3 0.4 0.4 0.55 0.55 | - | 0.1 0.24 0.3 0.4 0.4 0.55 0.55 | V |
| I _{IN} | Input Leakage Current | V _{IN} = 5.5 V or GND | 1.65 to 5.5 | - | _ | ±0.1 | - | ±1.0 | μΑ |
| I _{OFF} | Power Off Leakage Current | V_{IN} = 5.5 V or V_{OUT} = 5.5 V | 0 | - | _ | 1.0 | - | 10 | μΑ |
| I _{CC} | Quiescent Supply Current | $V_{IN} = V_{CC}$ or GND | 5.5 | - | _ | 1.0 | _ | 10 | μΑ |

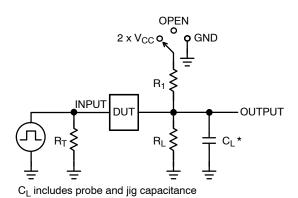
AC ELECTRICAL CHARACTERISTICS

| | | | | | T _A = 25°C | | T _A = −55°C | to +125°C | |
|--------------------|----------------------------|--|---------------------|-----|-----------------------|-----|------------------------|-----------|------|
| Symbol | Characteristic | Conditions | V _{CC} (V) | Min | Тур | Max | Min | Max | Unit |
| t _{PLH} , | Propagation Delay, | R_L = 1 M Ω , C_L = 15 pF | 1.65 to 1.95 | - | 7.7 | 10 | - | 10.5 | ns |
| t _{PHL} | (A or B or C or D) to Y | R_L = 1 M Ω , C_L = 15 pF | 2.3 to 2.7 | - | 4.2 | 7.5 | - | 8.0 | |
| | (Figures 3 and 4) | R_L = 1 M Ω , C_L = 15 pF | 3.0 to 3.6 | - | 3.0 | 5.2 | - | 5.5 | |
| | | $R_L = 500 \ \Omega$, $C_L = 50 \ pF$ | | - | 3.5 | 5.7 | - | 6.0 | |
| | | $R_L = 1 M\Omega$, $C_L = 15 pF$ | 4.5 to 5.5 | - | 2.3 | 4.5 | - | 4.8 | |
| | | $R_L = 500 \ \Omega$, $C_L = 50 \ pF$ | | - | 2.6 | 5.0 | - | 5.3 | |

CAPACITAVE CHARACTERISTICS

| Symbol | Parameter | Test Condition | Typical (T _A = 25 °C) | Unit |
|------------------|--|--|----------------------------------|------|
| C _{IN} | Input Capacitance | V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} | 2.5 | pF |
| C _{OUT} | Output Capacitance | V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} | 2.5 | pF |
| C _{PD} | Power Dissipation Capacitance (Note 5) | 10 MHz, V_{CC} = 3.3 V, V_{IN} = 0 V or V_{CC} | 9 | pF |
| | | 10 MHz, V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} | 11 | |

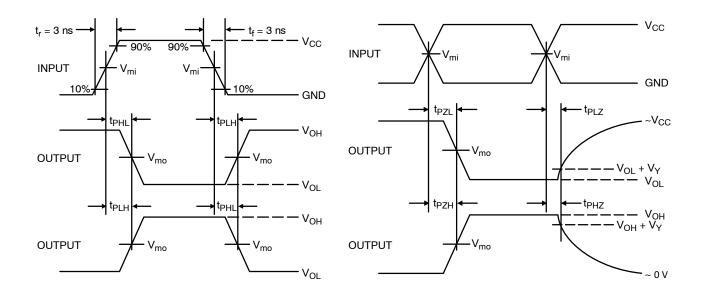
5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.



 R_T is Z_{OUT} of pulse generator (typicaly 50 Ω) f = 1 MHz

| Test | Switch Position | C _L , pF | R_L, Ω | R ₁ , Ω |
|-------------------------------------|--------------------|------------------------------|---------------|--------------------|
| t _{PLH} / t _{PHL} | Open | See AC Characteristics Table | | |
| t _{PLZ} / t _{PZL} | $2 \times V_{CC}$ | 50 | 500 | 500 |
| t _{PHZ} / t _{PZH} | GND | 50 | 500 | 500 |

Figure 2. Test Circuit



| | | Vm | | |
|---------------------|---------------------|-------------------------------------|---|--------------------|
| V _{CC} , V | V _{mi} , V | t _{PLH} , t _{PHL} | t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ} | V _Y , V |
| 1.65 to 1.95 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.15 |
| 2.3 to 2.7 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.15 |
| 3.0 to 3.6 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.3 |
| 4.5 to 5.5 | V _{CC} /2 | V _{CC} /2 | V _{CC} /2 | 0.3 |

| Figure 3. Switch | ing Waveforms |
|------------------|---------------|
|------------------|---------------|

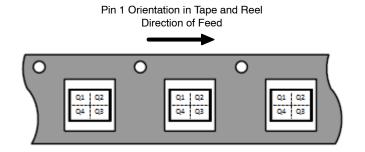
NLSF457

ORDERING INFORMATION

| Device | Package | Marking | Pin 1 Orientation (see bellow) | Shipping [†] |
|---------------|--------------------------|---------|--------------------------------|-----------------------|
| NLSF457MU3TCG | UDFN8, 1.45 x 1.0, 0.35P | AA | Q4 | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

* NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC – Q100 Qualified and PPAP Capable.





UDFN8, 1.45x1.0, 0.35P CASE 517EB ISSUE O DATE 27 AUG 2018 NDTES: A 1. DIMENSIONING AND TOLERANCING PER. D ASME Y14.5M, 1994. B PIN DNE REFERENCE 2. CONTROLLING DIMENSION: MILLIMETERS З. DIMENSION & APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN Ε 0.15 AND 0.20 FROM THE TERMINAL TIPS. 2X 0.10 C 4. PACKAGE DIMENSIONS EXCUSIVE OF BURRS AND MOLD FLASH. 2X 0.10 C EXPOSED COPPER MILLIMETERS TOP VIEW MIN. DIM NDM. MAX. 17-23 А 0.45 0.50 0.55 لـ ۵3 DETAIL B MOLD COMPOUND A3 -A1 ____ ____ 0.05 Α // 0.05 C DETAIL B 0.13 REF AЗ ALTERNATE CONSTRUCTIONS 0.20 0.15 0.25 b D 1.35 1.45 1.55 0.05 C AЗ Ε 0.90 1.00 1.10 A1 L1 SIDE VIEW -1 0.35 BSC e L 0.25 0.30 0.35 L1 0.05 0.10 0.15 L2 0.30 0.35 0.40 e DETAIL Α e/2 ALTERNATE TERMINAL 7X 0.35 0.48 PITCH 7X I 1 PACKAGE 1.18 DUTLINE L2 0.53 DETAIL 5 8 8X 0.22 -8X b RECOMMENDED 0.10 M C A B Φ MOUNTING FOOTPRINT 0.05@C NDTE 3 BOTTOM VIEW For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D. GENERIC **MARKING DIAGRAM*** *This information is generic. Please refer to XXM

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